

TABLE I-5 TO SUBPART I OF PART 98—DEFAULT EMISSION FACTORS (1-U_{ij}) FOR GAS UTILIZATION RATES (U_{ij}) AND BY-PRODUCT FORMATION RATES (B_{ijk}) FOR MEMS MANUFACTURINGTable I-5 to Subpart I of Part 98—Default Emission Factors (1-U_{ij}) for Gas Utilization Rates (U_{ij}) and By-Product Formation Rates (B_{ijk}) for MEMS Manufacturing

Process type factors	Process gas i											
	CF ₄	C ₂ F ₆	CHF ₃	CH ₂ F ₂	C ₃ F ₈	C ₄ F ₈	Remote	NF ₃				
	0.9	0.6	NA	NA	0.4	0.1	0.02	0.2	NA	NA	0.1	0.1
CVD Chamber Cleaning 1-U _i	NA	0.1	NA	NA	0.1	0.1	0.02	0.1	NA	NA	0.1	0.1
CVD Chamber Cleaning BCF ₄	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA
CVD Chamber Cleaning BC ₃ F ₈	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	0.4

Notes: NA = Not applicable; i.e., there are no applicable default emission factor measurements for this gas. This does not necessarily imply that a particular gas is not used in or emitted from a particular process sub-type or process type.

¹ Estimate includes multi-gas etch processes.

² Estimate reflects presence of low-k, carbide and multi-gas etch processes that may contain a C-containing fluorinated GHG additive.

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